

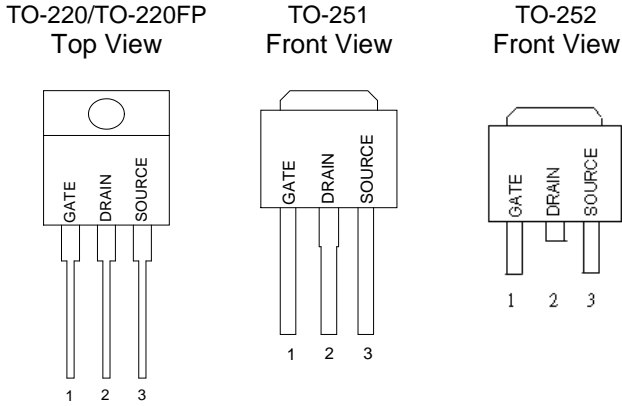
**GENERAL DESCRIPTION**

This advanced high voltage MOSFET is designed to withstand high energy in the avalanche mode and switch efficiently. This new high energy device also offers a drain-to-source diode with fast recovery time. Designed for high voltage, high speed switching applications such as power supplies, converters, power motor controls and bridge circuits.

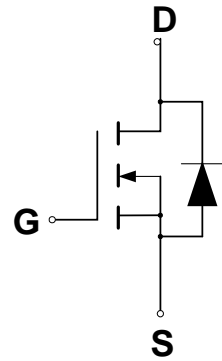
**FEATURES**

- ◆ SJ MOS
- ◆ Higher Current Rating
- ◆ Lower Rds(on)
- ◆ Lower Capacitances
- ◆ Lower Total Gate Charge

**PIN CONFIGURATION**



**SYMBOL**



N-Channel MOSFET

**ABSOLUTE MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Drain to Current – Continuous	$I_D$	18	A
– Pulsed	$I_{DM}$	54	
Gate-to-Source Voltage – Continue	$V_{GS}$	±20	V
Total Power Dissipation TO251/TO252	$P_D$	27	W
TO-220		125	
TO-220FP		31	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C
Single Pulse Drain-to-Source Avalanche Energy – $T_J = 25^\circ\text{C}$ ( $V_{DD} = 100\text{V}, V_{GS} = 10\text{V}, I_L = 5\text{A}, L = 10\text{mH}, R_G = 25$ )	$E_{AS}$	125	mJ
Thermal Resistance – Junction to Case TO251/TO252	$\theta_{JC}$	4.6	°C/W
TO-220		1	
TO220FP		4	
– Junction to Ambient TO251/TO252	$\theta_{JA}$	85	
TO-220		62.5	
TO-220FP		40	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	$T_L$	260	°C

**ORDERING INFORMATION**

Part Number	TOP MARK	Part Number	Packing Mthod	Note
GP18S50XN251 (Note1)	GP18S50X	TO-251	Tube	
GP18S50XN252 (Note1)	GP18S50X	TO-252	Tube	
GP18S50XN252TR (Note1)	GP18S50X	TO-252	Tape and Reel	
GP18S50XN220 (Note1)	GP18S50X	TO-220	Tube	
GP18S50XN220FP (Note1)	GP18S50X	TO-220FP	Tube	
GP18S50GN251 (Note2)	GP18S50G	TO-251	Tube	
GP18S50GN252 (Note2)	GP18S50G	TO-252	Tube	
GP18S50GN252TR (Note2)	GP18S50X	TO-252	Tape and Reel	
GP18S50GN220 (Note2)	GP18S50G	TO-220	Tube	
GP18S50GN220FP (Note2)	GP18S50G	TO-220FP	Tube	

**Note1:** X : Suffix for Halogen Free and PB Free Product

**Note2:** G : Suffix for PB Free Product

**ELECTRICAL CHARACTERISTICS**

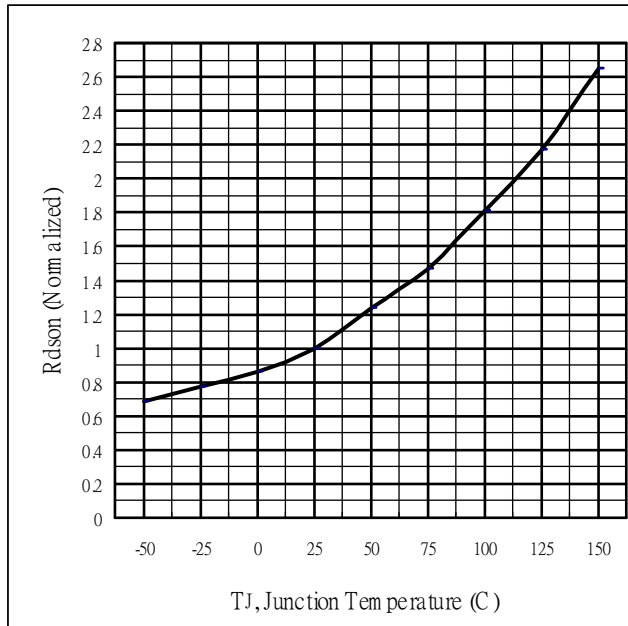
Unless otherwise specified,  $T_J = 25^\circ\text{C}$ .

Characteristic		Symbol	GP18S50			Units
			Min	Typ	Max	
Drain-Source Breakdown Voltage ( $V_{GS} = 0\text{ V}$ , $I_D = 250\ \mu\text{A}$ )		$V_{(BR)DSS}$	500			V
Drain-Source Leakage Current ( $V_{DS} = 500\text{ V}$ , $V_{GS} = 0\text{ V}$ )		$I_{DSS}$			1	$\mu\text{A}$
Gate-Source Leakage Current-Forward ( $V_{gsf} = 20\text{ V}$ , $V_{DS} = 0\text{ V}$ )		$I_{GSSF}$			100	nA
Gate-Source Leakage Current-Reverse ( $V_{gsr} = -20\text{ V}$ , $V_{DS} = 0\text{ V}$ )		$I_{GSSR}$			100	nA
Gate Threshold Voltage ( $V_{DS} = V_{GS}$ , $I_D = 250\ \mu\text{A}$ )		$V_{GS(th)}$	2	3	4	V
Static Drain-Source On-Resistance ( $V_{GS} = 10\text{ V}$ , $I_D = 6.2\text{A}$ ) *		$R_{DS(on)}$			0.19	
Input Capacitance	$(V_{DS} = 25\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1.0\text{ MHz}$ )	$C_{iss}$		1035		pF
Output Capacitance		$C_{oss}$		1283		pF
Reverse Transfer Capacitance		$C_{rss}$		12		pF
Turn-On Delay Time	$(V_{DD} = 250\text{ V}$ , $I_D = 6.2\text{ A}$ , $V_{GS} = 10\text{ V}$ , $R_G = 9.1\ \Omega$ ) *	$t_{d(on)}$		14.6		ns
Rise Time		$t_r$		43.2		ns
Turn-Off Delay Time		$t_{d(off)}$		64.6		ns
Fall Time		$t_f$		24		ns
Total Gate Charge	$(V_{DS} = 400\text{ V}$ , $I_D = 6.2\text{ A}$ , $V_{GS} = 10\text{ V}$ ) *	$Q_g$		25.75		nC
Gate-Source Charge		$Q_{gs}$		6.76		nC
Gate-Drain Charge		$Q_{gd}$		9.38		nC
<b>SOURCE-DRAIN DIODE CHARACTERISTICS</b>						
Forward On-Voltage(1)	$(I_S = 6.2\text{ A}$ , $d_i/d_t = 100\text{A}/\mu\text{s}$ )	$V_{SD}$			1.5	V
Forward Turn-On Time		$t_{on}$		**		ns
Reverse Recovery Time		$t_{rr}$		261.533		ns

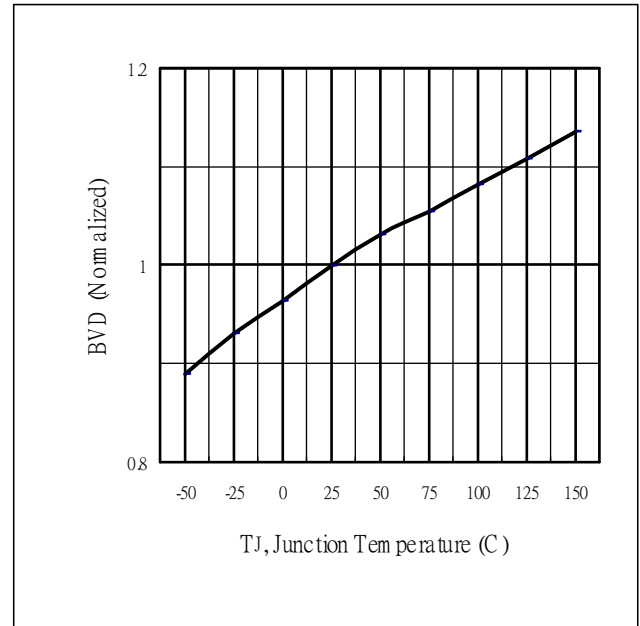
\* Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2\%$

\*\* Negligible, Dominated by circuit inductance

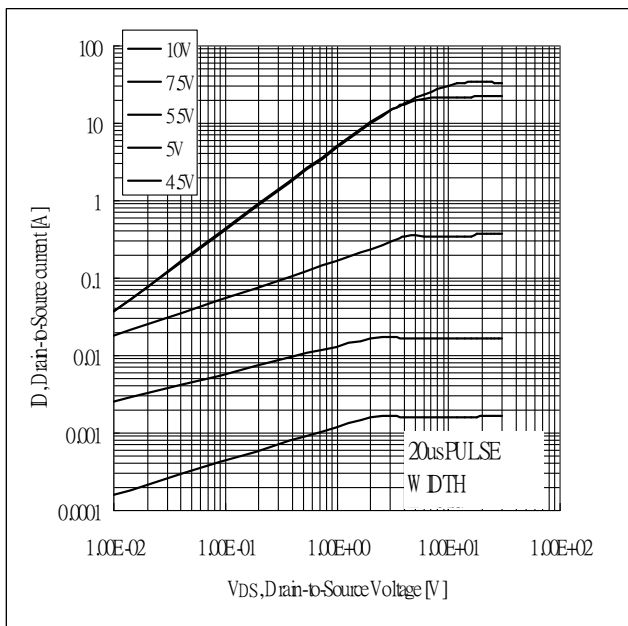
**TYPICAL ELECTRICAL CHARACTERISTICS**



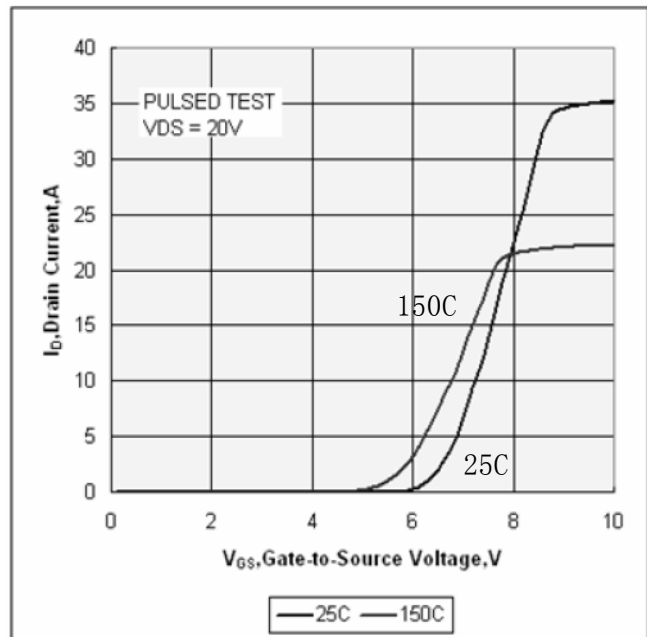
**Fig 1. On-Resistance Variation with vs. Temperature**



**Fig.2 Breakdown Voltage Variation vs. Temperature**



**Fig 3. Typical Output Characteristics**



**Fig 4. Typical Transfer Characteristics**

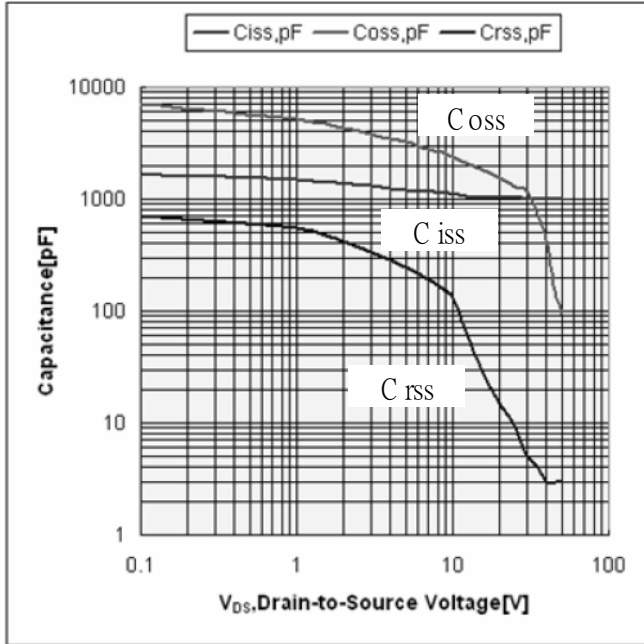


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

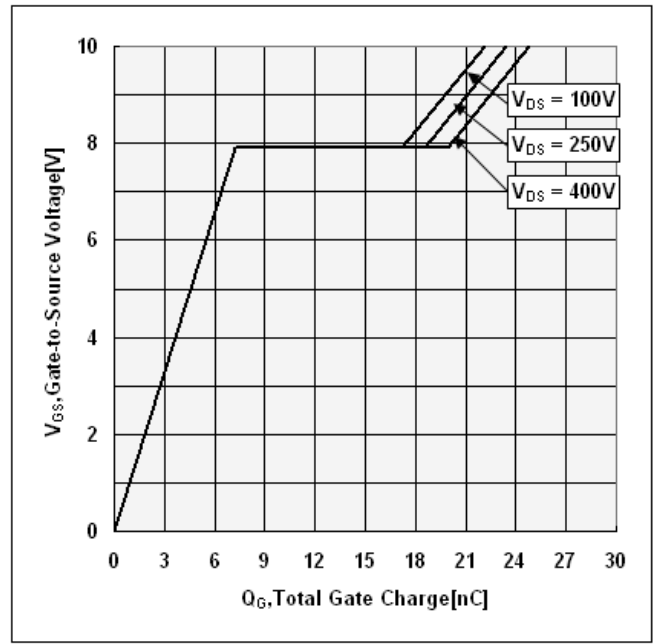
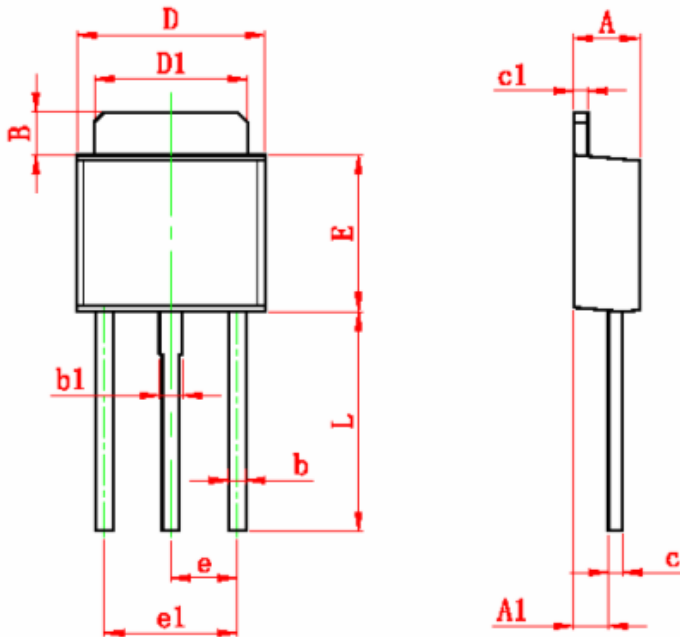


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

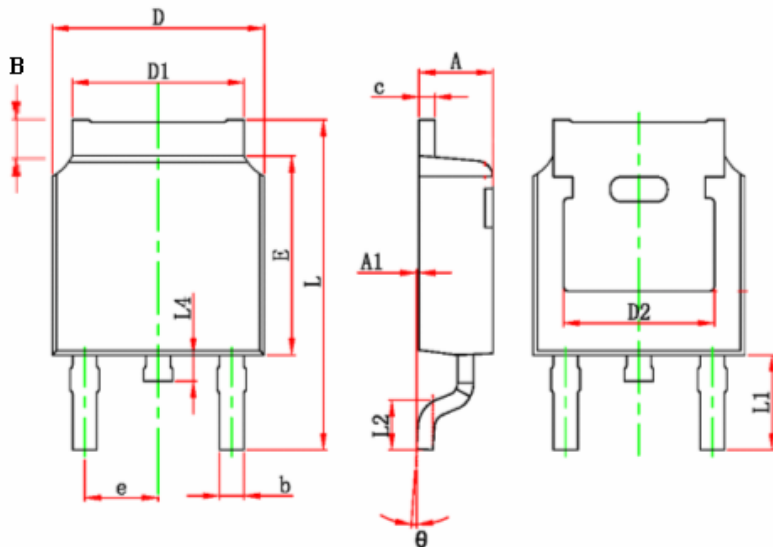
**PACKAGE DIMENSION**

**TO-251**



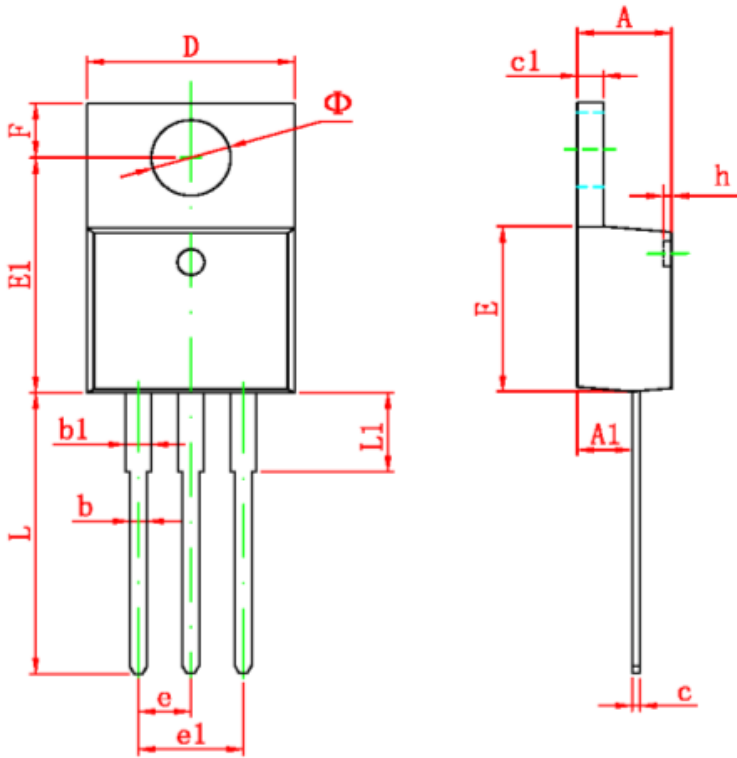
Symbol	Dimensions In Millimeters	
	Min.	Max
A	2.10	2.50
A1	0.90	1.35
B	0.90	1.65
b	0.45	0.75
b1	0.65	0.95
c	0.40	0.60
c1	0.40	0.60
D	6.30	6.80
D1	5.00	5.50
E	5.40	6.30
e	2.3 TYP.	
el	4.40	4.80
L	7.40	8.00

**TO-252**



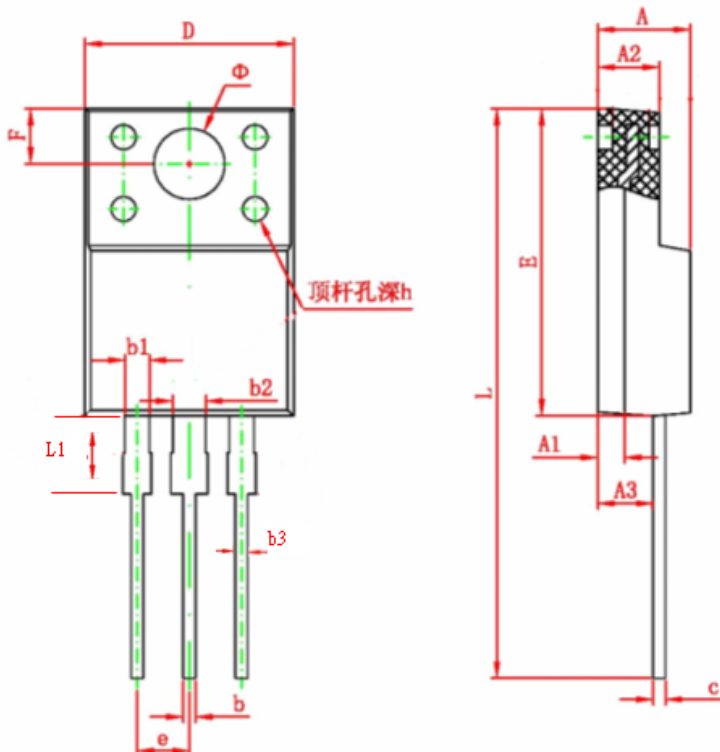
Symbol	Dimensions In Millimeters	
	Min.	Max
A	2.10	2.50
A1	0.90	1.35
B	0.90	1.65
b	0.45	0.90
c	0.40	0.60
D	6.30	6.80
D1	5.00	5.50
D2	4.83 TYP.	
E	5.90	6.30
e	2.3 TYP.	
L	9.30	10.50
L2	1.20	1.80
L4	0.60	1.00
θ	0.00	10.00

TO-220



Symbol	Dimensions In Millimeters	
	Min.	Max
A	4.40	4.80
A1	2.10	2.84
b	0.71	0.91
b1	1.17	1.37
c	0.30	0.60
c1	1.17	1.47
D	9.40	10.60
E	8.40	9.60
e	2.54 TYP.	
e1	4.90	5.60
F	3.00 REF.	
Φ	3.50 REF.	
h	0.00	0.30
L	12.50	14.00
L1	3.50	4.00

TO-220FP



Symbol	Dimensions In Millimeters	
	Min.	Max
A	3.80	4.70
A1	1.3 REF.	
A2	2.20	3.20
A3	2.10	3.20
b	0.30	0.95
b1	1.00	1.75
b2	1.00	1.75
b3	0.50	0.80
c	0.30	0.90
D	9.90	10.40
E	14.60	16.20
e	2.54 TYP.	
F	3.00 REF.	
Φ	3.50 REF.	
h	0.00	0.30
L	28.00	30.00
L1	3.20	3.55

## IMPORTANT NOTICE

Great Power Microelectronic Corporation (GP) reserves the right to make changes to its products or to discontinue any integrated circuit product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

A few applications using integrated circuit products may involve potential risks of death, personal injury, or severe property or environmental damage. GP integrated circuit products are not designed, intended, authorized, or warranted to be suitable for use in life-support applications, devices or systems or other critical applications. Use of GP products in such applications is understood to be fully at the risk of the customer. In order to minimize risks associated with the customer's applications, the customer should provide adequate design and operating safeguards.



虹冠電子工業股份有限公司  
Champion Microelectronic Corporation  
Web:<http://www.champion-micro.com/>



深圳市冠順微電子股份有限公司  
Shenzhen Great Power Co., Ltd  
Web:[http:// www.greatpowermicro.com](http://www.greatpowermicro.com)

---

### 臺灣

新北市汐止區新台五路一段 96 號 21F  
21F., No. 96, Sec. 1, Sintai 5th Rd.,  
Sijhih City, Taipei County 22102,  
Taiwan, R.O.C.  
TEL: +886-2-2696 3558  
FAX: +886-2-2696 3559

---

### 深圳

深圳市福田区深南大道 7002 号财富广场 A 座 4V,  
4V, Tower A, Fortune Plaza, No. 7002, Shennan  
Road, Futian District, Shenzhen City, China  
PC : 518040  
TEL: +86-755-83709176  
FAX: +86-755-83709276

---